

Title (en)
COMPONENT HOUSING FOR SURFACE MOUNTING A SEMICONDUCTOR COMPONENT

Title (de)
BAUELEMENTGEHÄUSE FÜR EINE OBERFLÄCHENMONTAGE EINES HALBLEITER-BAUELEMENTES

Title (fr)
BOITIER DE COMPOSANT POUR MONTER EN SURFACE UN COMPOSANT A SEMICONDUCTEUR

Publication
EP 0907965 A1 19990414 (DE)

Application
EP 97931678 A 19970627

Priority
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• DE 19626082 A 19960628
• DE 19626098 A 19960628

Abstract (en)
[origin: US6058020A] A component housing for surface mounting of a semiconductor component on a component-mounting surface of a printed circuit board. The component housing including a chip carrier made of an electrically insulating material and having an approximately planar chip carrier area, a semiconductor chip, preferably having an integrated electronic circuit, secured on the chip carrier area, and electrode terminals having a surface-mountable configuration. The electrode terminals penetrating through the chip carrier and electrically connected to the semiconductor chip. A distance between the component-mounting surface of the printed circuit board and outer delimiting areas of the chip carrier which face the component-mounting surface of the printed circuit board increases continuously from an edge region to a central region of the chip carrier.

IPC 1-7
H01L 23/13

IPC 8 full level
H01L 23/28 (2006.01); **H01L 23/047** (2006.01); **H01L 23/13** (2006.01); **H01L 23/24** (2006.01); **H01L 23/31** (2006.01); **H01L 23/498** (2006.01); **H05K 3/30** (2006.01); **H05K 1/18** (2006.01)

CPC (source: EP US)
H01L 23/047 (2013.01 - EP US); **H01L 23/13** (2013.01 - EP US); **H01L 23/24** (2013.01 - EP US); **H01L 23/3107** (2013.01 - EP US); **H01L 23/49861** (2013.01 - EP US); **H05K 3/303** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/49** (2013.01 - EP US); **H01L 2224/05554** (2013.01 - EP US); **H01L 2224/056** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/48465** (2013.01 - EP US); **H01L 2224/49175** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/10161** (2013.01 - EP US); **H01L 2924/15153** (2013.01 - EP US); **H01L 2924/15165** (2013.01 - EP US); **H01L 2924/16195** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H05K 1/181** (2013.01 - EP US); **H05K 2201/09036** (2013.01 - EP US); **H05K 2201/10568** (2013.01 - EP US); **H05K 2201/10689** (2013.01 - EP US); **H05K 2201/10931** (2013.01 - EP US); **Y02P 70/50** (2015.11 - EP US)

C-Set (source: EP US)
1. **H01L 2224/48091 + H01L 2924/00014**
2. **H01L 2924/181 + H01L 2924/00012**
3. **H01L 2224/48465 + H01L 2224/48247 + H01L 2924/00**
4. **H01L 2224/49175 + H01L 2224/48247 + H01L 2924/00**
5. **H01L 2224/49175 + H01L 2224/48465 + H01L 2924/00**
6. **H01L 2224/48465 + H01L 2224/48091 + H01L 2924/00**
7. **H01L 2224/056 + H01L 2924/00014**
8. **H01L 2924/00014 + H01L 2224/45099**
9. **H01L 2924/00014 + H01L 2224/85399**
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